

IN THE CLAIMS:

Note that the full text of all claims (including those not being amended within this paper) may also be included to provide the convenience of a complete set of claims for easy review:

1. (Canceled without prejudice or disclaimer)

2. (Canceled without prejudice or disclaimer)

3. (Amended) A planarizing support layer provided on a bumped surface of one of a bumped-die and bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering at least a substantial majority of bump-bodies of bumps on the bumped surface, while leaving a remainder portion of the bump-bodies exposed; and

an adhesive protection tape including a flexible conforming layer applied to the under-fill layer, the conforming layer to cover the remainder portion of the bump-bodies not covered by the under-fill layer, to further improve a planarity of the support layer.

4. (Amended) A planarizing support layer provided on a bumped surface of one of a bumped-die and bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support

during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering an entirety of bump-bodies of bumps on the bumped surface.

5. (Original) A support layer as claimed in claim 4, the support layer further comprising an adhesive protection tape applied to the under-fill layer.

6. (Original) A support layer as claimed in claim 4, the under-fill layer being of a predetermined thickness beyond a height thickness of the bump-bodies, to provide additional under-fill material to under-fill structures other than the bumps during any mounting/under-fill process.

7. (Amended) A support layer as claimed in claim 4, the under-fill layer comprising a polymer material.

8. (Amended) A support layer as claimed in claim 4, the under-fill layer comprising one of a thermoplastic and thermoset polymer material.

9. (Amended) A support layer as claimed in claim 4, the under-fill layer comprising one of a thermoplastic material, thermoset material, light-curable material and a chemical-curable material.

10. (Amended) A support layer as claimed in claim 4, the under-fill layer comprising an opaque material to provide at least one of light, ultra-violet (UV) light, and radiation protection to a surface of the bumped-die or bumped-wafer.

11. (Canceled without prejudice or disclaimer)

12. (Canceled without prejudice or disclaimer)

13. (Amended) A back-grind/mounting arrangement comprising one of a bumped-die and bumped wafer comprising: a planarizing support layer provided on a bumped surface of the bumped-die or bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering at least a substantial majority of bump-bodies of bumps on the bumped surface, while leaving a remainder portion of the bump-bodies exposed; and

an adhesive protection tape including a flexible conforming layer applied to the under-fill layer, the conforming layer to cover the remainder portion of the bump-bodies not covered by the under-fill layer, to further improve a planarity of the support layer.

14. (Amended) An arrangement as claimed in claim 13, the arrangement further comprising a secondary under-fill layer to under-fill at least one of: the

reminder portion of the bump-bodies not covered by the under-fill layer, and structures other than the bumps as encountered during any mounting process.

15. (Amended) A back-grind/mounting arrangement comprising one of a bumped-die and bumped wafer comprising: a planarizing support layer provided on a bumped surface of the bumped-die or bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering an entirety of bump-bodies of bumps on the bumped surface.

16. (Original) An arrangement as claimed in claim 15, the support layer further comprising an adhesive protection tape applied to the under-fill layer.

17. (Original) An arrangement as claimed in claim 15, the under-fill layer being of a predetermined thickness beyond a height thickness of the bump-bodies, to provide additional under-fill material to under-fill structures other than the bumps as encountered during any mounting process.

18. (Amended) An arrangement as claimed in claim 15, the under-fill layer comprising a polymer material.

19. (Amended) An arrangement as claimed in claim 15, the under-fill layer comprising one of a thermoplastic and thermoset polymer material.

20. (Amended) An arrangement as claimed in claim 15, the under-fill layer comprising one of a thermoplastic material, thermoset material, light-curable material and a chemical-curable material.

21. (Amended) An arrangement as claimed in claim 15, the under-fill layer comprising an opaque material to provide at least one of light, ultra-violet (UV) light, and radiation protection to a surface of the bumped-die or bumped-wafer.

22. (Amended) An arrangement as claimed in claim 15, wherein the arrangement is a flip-chip back-grind/mounting arrangement.

23. (Canceled without prejudice or disclaimer)

24. (Canceled without prejudice or disclaimer)

25. (Amended) A back-grind/mounting method useable with either one of a bumped-die and bumped wafer, the method comprising: providing a planarizing support layer on a bumped surface of the bumped-die or bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill

material during any mounting/under-fill process, the under-fill layer covering at least a substantial majority of bump-bodies of bumps on the bumped surface, while leaving a remainder portion of the bump-bodies exposed; and

an adhesive protection tape including a flexible conforming layer applied to the under-fill layer, the conforming layer to cover the remainder portion of the bump-bodies not covered by the under-fill layer, to further improve a planarity of the support layer.

26. (Amended) A method as claimed in claim 25, the method further comprising: providing a secondary under-fill layer to under-fill at least one of: the remainder portion of the bump-bodies not covered by the under-fill layer, and structures other than the bumps as encountered during any mounting process.

27. (Original) A back-grind/mounting method useable with either one of a bumped-die and bumped wafer, the method comprising: providing a planarizing support layer on a bumped surface of the bumped-die or bumped-wafer, the support layer comprising a pre-back-grind under-fill layer both to provide substantially planar back-grind wafer support during any back-grind process, and to provide under-fill material during any mounting/under-fill process, the under-fill layer covering an entirety of bump-bodies of bumps on the bumped surface.

28. (Original) A method as claimed in claim 27, the support layer further comprising an adhesive protection tape applied to the under-fill layer.

29. (Original) A method as claimed in claim 27, the under-fill layer being of a predetermined thickness beyond a height thickness of the bump-bodies, to provide additional under-fill material to under-fill structures other than the bumps as encountered during any mounting process.

30. (Amended) A method as claimed in claim 27, the under-fill layer comprising a polymer material.

31. (Amended) A method as claimed in claim 27, the under-fill layer comprising one of a thermoplastic and thermoset polymer material.

32. (Amended) A method as claimed in claim 27, the under-fill layer comprising one of a thermoplastic material, thermoset material, light-curable material and a chemical-curable material.

33. (Amended) A method as claimed in claim 27, the under-fill layer comprising an opaque material to provide at least one of light, ultra-violet (UV) light, and radiation protection to a surface of the bumped-die or bumped-wafer.

34. (Amended) A method as claimed in claim 27, wherein the method is a flip-chip back-grind/mounting method.